PCB:

FABRICATE TO IPC 6012 CLASS 2 VENDOR MARKINGS ON BOTTOM SIDE ONLY! VENDOR MARKINGS IN SILKSCREEN ONLY!

FIDUCIAL MARKS: FID1, FID2, FID3

DESIGNED BY:

ENG. ANDRÉ A. M. ARAÚJO

	Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
	F.Silkscreen	Top Silk Screen	Not specified	0 mm	White	1	0
	F.Paste	Top Solder Paste		0 mm		1	0
Н	F.Mask	Top Solder Mask	Not specified	0.01 mm	Green	3.3	0
	L1 - TOP (SIG-PWR)	copper		0.035 mm		1	0
	Dielectric 1	prepreg	FR4	0.0994 mm	FR4 natural	4.1	0
	L2 - GND	copper		0.0175 mm		1	0
	Dielectric 2	core	FR4	1.265 mm	FR4 natural	4.6	0
	L3 - GND	copper		0.0175 mm		1	0
	Dielectric 3	prepreg	FR4	0.0994 mm	FR4 natural	4.1	0
D	L4 - BOTTOM (SIG-PWR)	copper		0.035 mm		1	0
	B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Green	3.3	0
	B.Paste	Bottom Solder Paste		0 mm		1	0
	B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	White	1	0

## **BOARD CHARACTERISTICS**

1.5888 mm Copper Layer Count: Board Thickness:

Board overall dimensions: 100.0000 mm x 82.0000 mm

Min track/spacing: 0.1270 mm / 0.1270 mm Min hole diameter: 0.3000 mm

Copper Finish: HAL SnPb Impedance Control: Yes Castellated pads: No Plated Board Edge: No

Edge card connectors: Νo

Revision Log: Rev: 00 — Initial Release Rev: 01 — Improved images on silkscreen Rev: 02 — Corrected minor issues on D2 and U6 symbols/footprints

Eng. André A. M. Araújo

Mechatronix Lab

File: EMBARCADOS - CURSO PCB.kicad\_pcb

Title: EMBARCADOS - CURSO PCB Size: A4 Date: 2025-02-09 Rev: 02 KiCad E.D.A. 8.0.6 ld: 1/1